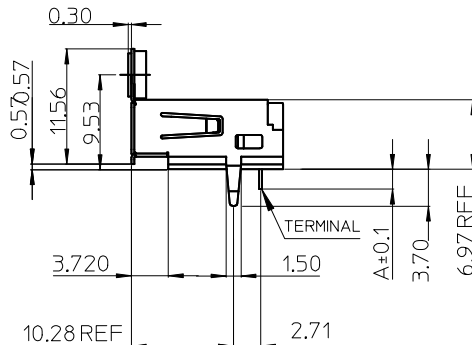
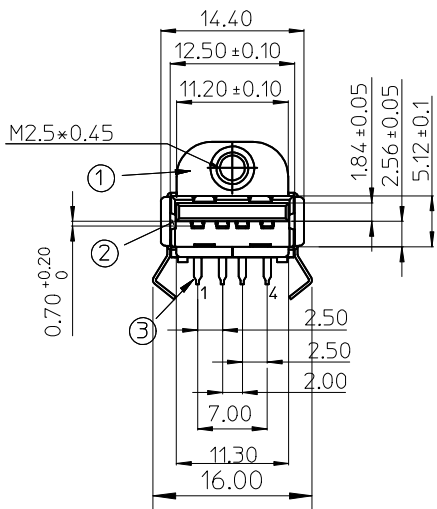
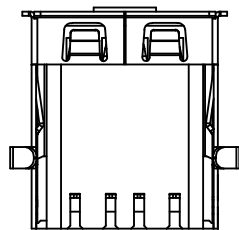


PCB LAYOUT (BOTTOM VIEW)



NOTES:

- MATERIAL:
 - ① METAL SHELL: COPPER ALLOY. SCREW: BRASS
 - ② HOUSING: SEE CHART, 30% GLASS FIBER FILLES, UL94-V0.
 - ③ TERMINAL: PHOSPHOR BRONZE
- PLATING:
 - TERMINAL:
 - CONTACT AREA: (a) GOLD FLASH.
 - (b) GOLD (Au), THICKNESS=0.76 μM/30MNCH MINIMUM.
 - SOLDER TAIL: TIN PLATED, THICKNESS=1.875 μM/75MNCH MINIMUM.
 - UNDER PLATED: NICKEL (Ni), THICKNESS=1.25 μM/50MNCH MINIMUM.
 - METAL SHELL: SEE CHART.
- RECOMMENDED PCB THICKNESS: SEE CHART
- PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002
FOR NON IR REFER TO PS-67643-003
- TORQUE FORCE SPEC: 2.50kg-cm Min, MEASURED AT BROKEN POINT.
- TEST SUMMARY: FOR IR REFER TO TS-67643-002
FOR NON IR REFER TO TS-67643-003
- PACKAGE: REFER TO PK-67643-002
- LEAD FREE AND ROHS COMPLIANCE PRODUCT



REVISED EC NO: DRWN: FYANG05 CHKD: APPR:	DESCRIPTION 2013/05/09	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY IVY-LIN	DATE 2005/04/01	TITLE USB A TYPE RCPT SGL RA THRHOLE WITH UPPER FLG (LEAD-FREE VERSION)		
			4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± 0.25 ± ---	CHECKED BY ALL IN			
			ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY WWSCHANG	DATE 2005/04/01	MOLEX INCORPORATED	
			SEE SHEET 2		MATERIAL NO.		DOCUMENT NO. SD-67643-004	SHEET NO. 1 OF 2		
					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0990	POLYESTER	BLACK	GOLD FLSAH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=2.54 μM/100μNCH UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	NON IR
67643-1990	POLYESTER	WHITE			REFLOW PROCESS
67643-2990	HIGH TEMPERATURE NYLON	BLACK	FOR IR		
67643-3990	HIGH TEMPERATURE NYLON	WHITE	REFLOW PROCESS		
67643-0991	POLYESTER	BLACK	GOLD PLATING 0.76 μM/30μNCH	NON IR REFLOW PROCESS: MATTE TIN PLATED. THICKNESS=2.00 μM/80μNCH UNDER PLATE:NICKEL (Ni).	NON IR
67643-1991	POLYESTER	WHITE			REFLOW PROCESS
67643-2991	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3991	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
PCB THICKNESS		1.60±0.05			
DIMENSION "A"		2.60			

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0980	HIGH TEMPERATURE NYLON	BLACK	GOLD FLSAH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=2.54 μM/100μNCH UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	FOR IR
67643-1980	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
67643-0981	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 0.76 μM/30μNCH		
67643-1981	HIGH TEMPERATURE NYLON	WHITE			
PCB THICKNESS		1.20±0.05			
DIMENSION "A"		2.00			

REVISED ECT NO: DRAWN: FYANG05 CHKD: APPR:	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
					mm	INCH	DRAWN BY	DATE	TITLE			
			4 PLACES ± --- ± ---		± ---	± ---	IVY-LIN	2005/04/01	USB A TYPE RCPT SGL RA THRHOLE WITH UPPER FLG (LEAD-FREE VERSION)			
			3 PLACES ± --- ± ---		± ---	± ---	CHECKED BY	DATE	MOLEX INCORPORATED			
2 PLACES ± 0.25 ± ---		± 0.25	± ---	ALL IN	2005/04/01	APPROVED BY		DATE	DOCUMENT NO.			
1 PLACE ± 0.25 ± ---		± 0.25	± ---	ANGULAR ± 3 °		WWSCHANG		2005/04/01	SD-67643-004			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO.		SHEET NO.		2 OF 2				
		SIZE A4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								